Product data sheet

1. General description

The 74LVC2G00 is a dual 2-input NAND gate. Inputs can be driven from either 3.3~V or 5~V devices. This feature allows the use of these devices as translators in mixed 3.3~V and 5~V environments.

Schmitt-trigger action at all inputs makes the circuit tolerant of slower input rise and fall times.

This device is fully specified for partial power down applications using I_{OFF} . The I_{OFF} circuitry disables the output, preventing the potentially damaging backflow current through the device when it is powered down.

2. Features and benefits

- Wide supply voltage range from 1.65 V to 5.5 V
- 5 V tolerant outputs for interfacing with 5 V logic
- High noise immunity
- ±24 mA output drive (V_{CC} = 3.0 V)
- CMOS low power dissipation
- I_{OFF} circuitry provides partial Power-down mode operation
- Complies with JEDEC standard:
 - JESD8-7 (1.65 V to 1.95 V)
 - JESD8-5 (2.3 V to 2.7 V)
 - JESD8-B/JESD36 (2.7 V to 3.6 V)
- Latch-up performance exceeds 250 mA
- Direct interface with TTL levels
- Overvoltage tolerant inputs to 5.5 V
- ESD protection:
 - HBM: ANSI/ESDA/JEDEC JS-001 class 2 exceeds 2000 V
 - CDM: ANSI/ESDA/JEDEC JS-002 class C3 exceeds 1000 V
- · Multiple package options
- Specified from -40 °C to +85 °C and -40 °C to +125 °C



Dual 2-input NAND gate

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74LVC2G00DP	-40 °C to +125 °C	TSSOP8	plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm	SOT505-2
74LVC2G00DC	-40 °C to +125 °C	VSSOP8	plastic very thin shrink small outline package; 8 leads; body width 2.3 mm	SOT765-1
74LVC2G00GT	-40 °C to +125 °C	XSON8	plastic extremely thin small outline package; no leads; 8 terminals; body 1 × 1.95 × 0.5 mm	SOT833-1
74LVC2G00GM	-40 °C to +125 °C	XQFN8	plastic, extremely thin quad flat package; no leads; 8 terminals; body 1.6 × 1.6 × 0.5 mm	SOT902-2
74LVC2G00GN	-40 °C to +125 °C	XSON8	extremely thin small outline package; no leads; 8 terminals; body 1.2 × 1.0 × 0.35 mm	SOT1116
74LVC2G00GS	-40 °C to +125 °C	XSON8	extremely thin small outline package; no leads; 8 terminals; body 1.35 × 1.0 × 0.35 mm	SOT1203
74LVC2G00GX	-40 °C to +125 °C	X2SON8	plastic thermal enhanced extremely thin small outline package; no leads; 8 terminals; body 1.35 × 0.8 × 0.32 mm	SOT1233-2

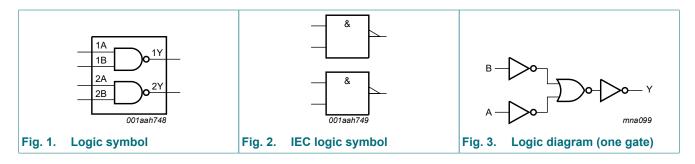
4. Marking

Table 2. Marking codes

Type number	Marking code[1]
74LVC2G00DP	V2G00
74LVC2G00DC	V00
74LVC2G00GT	V00
74LVC2G00GM	V00
74LVC2G00GN	VA
74LVC2G00GS	VA
74LVC2G00GX	VA

^[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram

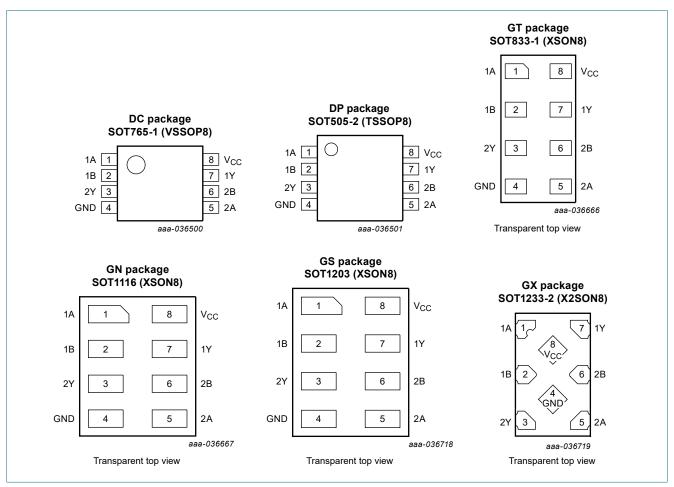


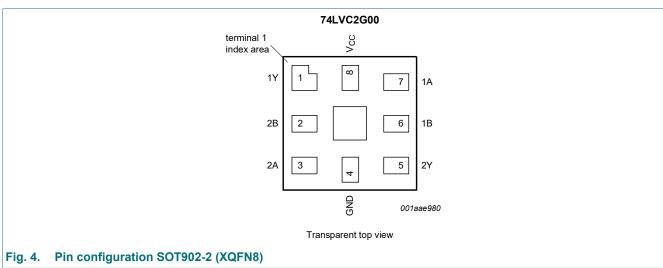
74LVC2G00

Dual 2-input NAND gate

6. Pinning information

6.1. Pinning





Dual 2-input NAND gate

6.2. Pin description

Table 3. Pin description

Symbol	Pin		Description	
	SOT505-2, SOT765-1, SOT833-1, SOT1116, SOT1203 and SOT1233-2	SOT902-2		
1A, 2A	1, 5	7, 3	data input	
1B, 2B	2, 6	6, 2	data input	
GND	4	4	ground (0 V)	
1Y, 2Y	7, 3	1, 5	data output	
V _{CC}	8	8	supply voltage	

7. Functional description

Table 4. Function table

 $H = HIGH \ voltage \ level; \ L = LOW \ voltage \ level.$

Input		Output
nA	nB	nY
L	L	Н
L	Н	Н
Н	L	Н
Н	Н	L

Dual 2-input NAND gate

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V _{CC}	supply voltage			-0.5	+6.5	V
VI	input voltage		[1]	-0.5	+6.5	V
Vo	output voltage	Active mode	[1]	-0.5	V _{CC} + 0.5	V
		Power-down mode; V _{CC} = 0 V	[1]	-0.5	+6.5	V
I _{IK}	input clamping current	V _I < 0 V		-50	-	mA
I _{OK}	output clamping current	$V_O < 0 \text{ V or } V_O > V_{CC}$		-	±50	mA
Io	output current	V _O = 0 V to V _{CC}		-	±50	mA
I _{CC}	supply current			-	100	mA
I _{GND}	ground current			-100	-	mA
T _{stg}	storage temperature			-65	+150	°C
P _{tot}	total power dissipation	T_{amb} = -40 °C to +125 °C				
		SOT505-2 (TSSOP8) SOT765-1 (VSSOP8) SOT833-1 (XSON8) SOT902-2 (XQFN8) SOT1116 (XSON8) SOT1203 (XSON8)	[2]	-	250	mW
		SOT1233-2 package	[3]	-	300	mW

^[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

For SOT765-1 (VSSOP8) package: P_{tot} derates linearly with 4.9 mW/K above 99 °C.

For SOT833-1 (XSON8) package: Ptot derates linearly with 3.1 mW/K above 68 °C.

For SOT902-2 (XQFN8) packages: P_{tot} derates linearly with 4.1 mW/K above 89 °C.

For SOT1116 (XSON8) package: P_{tot} derates linearly with 4.2 mW/K above 90 °C.

For SOT1203 (XSON8) package: P_{tot} derates linearly with 3.6 mW/K above 81 $^{\circ}\text{C}.$

9. Recommended operating conditions

Table 6. Operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		1.65	5.5	V
V _I	input voltage		0	5.5	V
Vo	output voltage	Active mode	0	V _{CC}	V
		Power-down mode; V _{CC} = 0 V	0	5.5	V
T _{amb}	ambient temperature		-40	+125	°C
Δt/ΔV	input transition rise and fall rate	V _{CC} = 1.65 V to 2.7 V	-	20	ns/V
		V _{CC} = 2.7 V to 5.5 V	-	10	ns/V

^[2] For SOT505-2 (TSSOP8) package: P_{tot} derates linearly with 4.6 mW/K above 96 °C.

^[3] For SOT1233-2 (X2SON8) package: Ptot derates linearly with 7.7 mW/K above 118 °C.

Dual 2-input NAND gate

10. Static characteristics

Table 7. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
T _{amb} = -4	0 °C to +85 °C				1	
V _{IH}	HIGH-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}	-	-	V
		V _{CC} = 2.3 V to 2.7 V	1.7	-	-	V
		V _{CC} = 2.7 V to 3.6 V	2.0	-	-	V
		V _{CC} = 4.5 V to 5.5 V	0.7 × V _{CC}	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 1.65 V to 1.95 V	-	-	0.35 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.7	V
		V _{CC} = 2.7 V to 3.6 V	-	-	0.8	V
		V _{CC} = 4.5 V to 5.5 V	-	-	0.3 × V _{CC}	V
V _{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		I _O = -100 μA; V _{CC} = 1.65 V to 5.5 V	V _{CC} - 0.1	-	-	V
		I _O = -4 mA; V _{CC} = 1.65 V	1.2	1.53	-	V
		I _O = -8 mA; V _{CC} = 2.3 V	1.9	2.13	-	V
		I _O = -12 mA; V _{CC} = 2.7 V	2.2	2.50	-	V
		I _O = -24 mA; V _{CC} = 3.0 V	2.3	2.60	-	V
		I _O = -32 mA; V _{CC} = 4.5 V	3.8	4.10	-	V
V _{OL}	LOW-level output voltage	$V_{I} = V_{IH}$ or V_{IL}				
		I _O = 100 μA; V _{CC} = 1.65 V to 5.5 V	-	-	0.1	V
		I _O = 4 mA; V _{CC} = 1.65 V	-	0.08	0.45	V
		I _O = 8 mA; V _{CC} = 2.3 V	-	0.14	0.3	V
		I_{O} = 12 mA; V_{CC} = 2.7 V	-	0.19	0.4	V
		$I_O = 24 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	0.37	0.55	V
		I_{O} = 32 mA; V_{CC} = 4.5 V	-	0.43	0.55	V
l _l	input leakage current	$V_I = 5.5 \text{ V or GND}$; $V_{CC} = 0 \text{ V to } 5.5 \text{ V}$	-	±0.1	±1	μΑ
I_{OFF}	power-off leakage current	V_{I} or $V_{O} = 5.5 \text{ V}$; $V_{CC} = 0 \text{ V}$	-	±0.1	±2	μΑ
I _{CC}	supply current	$V_I = 5.5 \text{ V or GND};$ $V_{CC} = 1.65 \text{ V to } 5.5 \text{ V}; I_O = 0 \text{ A}$	-	0.1	4	μA
Δl _{CC}	additional supply current	per pin; V _I = V _{CC} - 0.6 V; V _{CC} = 2.3 V to 5.5 V; I _O = 0 A	-	5	500	μΑ
Cı	input capacitance		-	2.5	-	pF

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Dual 2-input NAND gate

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
T _{amb} = -4	0 °C to +125 °C			'		
V _{IH}	HIGH-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}	-	-	V
		V _{CC} = 2.3 V to 2.7 V	1.7	-	-	V
		V _{CC} = 2.7 V to 3.6 V	2.0	-	-	V
		V _{CC} = 4.5 V to 5.5 V	0.7 × V _{CC}	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 1.65 V to 1.95 V	-	-	0.35 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.7	V
		V _{CC} = 2.7 V to 3.6 V	-	-	- V - V 0.35 × V _{CC} V 0.7 V 0.8 V 0.3 × V _{CC} V - V - V - V - V - V - V - V 0.1 V 0.70 V 0.45 V 0.80 V 0.80 V ±1 µ ±2 µ	V
		V _{CC} = 4.5 V to 5.5 V	-	-	0.3 × V _{CC}	V
V _{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		I _O = -100 μA; V _{CC} = 1.65 V to 5.5 V	V _{CC} - 0.1	-	-	V
		I _O = -4 mA; V _{CC} = 1.65 V	0.95	-	-	V
		I _O = -8 mA; V _{CC} = 2.3 V	1.7	-	-	V
		I _O = -12 mA; V _{CC} = 2.7 V	1.9	-	-	V
		I _O = -24 mA; V _{CC} = 3.0 V	2.0	-	-	V
		I _O = -32 mA; V _{CC} = 4.5 V	3.4	-	-	V
V _{OL}	LOW-level output voltage	$V_{I} = V_{IH}$ or V_{IL}				
		I _O = 100 μA; V _{CC} = 1.65 V to 5.5 V	-	-	0.1	V
		I _O = 4 mA; V _{CC} = 1.65 V	-	-	0.70	V
		I _O = 8 mA; V _{CC} = 2.3 V	-	-	0.45	V
		I _O = 12 mA; V _{CC} = 2.7 V	-	-	0.60	V
		I _O = 24 mA; V _{CC} = 3.0 V	-	-	- V 0.35 × V _{CC} V 0.7 V 0.8 V 0.3 × V _{CC} V - V - V - V - V 0.1 V 0.70 V 0.45 V 0.80 V 0.80 V ±1 µA ±2 µA	V
		I _O = 32 mA; V _{CC} = 4.5 V	-	-	0.80	V
l _l	input leakage current	$V_I = 5.5 \text{ V or GND}$; $V_{CC} = 0 \text{ V to } 5.5 \text{ V}$	-	-	±1	μΑ
I _{OFF}	power-off leakage current	V_{I} or $V_{O} = 5.5 \text{ V}$; $V_{CC} = 0 \text{ V}$	-	-	±2	μΑ
I _{CC}	supply current	V _I = 5.5 V or GND; V _{CC} = 1.65 V to 5.5 V; I _O = 0 A	' ₁ = 5.5 V or GND; -		4	μΑ
ΔI _{CC}	additional supply current	per pin; V _I = V _{CC} - 0.6 V; V _{CC} = 2.3 V to 5.5 V; I _O = 0 A	-	-	500	μΑ

^[1] All typical values are measured at T_{amb} = 25 °C.

Product data sheet

Dual 2-input NAND gate

11. Dynamic characteristics

Table 8. Dynamic characteristics

Voltages are referenced to GND (ground 0 V); for test circuit see Fig. 6.

Symbol	Parameter	Conditions	T_{amb} = -40 °C to +85 °C		T _{amb} = -40 °C to +125 °C		Unit	
			Min	Typ[1]	Max	Min	Max	
t _{pd}	propagation delay	nA, nB to nY; see Fig. 5 [2]						
		V _{CC} = 1.65 V to 1.95 V	1.2	3.5	8.6	1.2	10.8	ns
		V _{CC} = 2.3 V to 2.7 V	0.7	2.3	4.8	0.7	6.0	ns
		V _{CC} = 2.7 V	0.7	3.0	5.6	0.7	7.0	ns
		V _{CC} = 3.0 V to 3.6 V	0.7	2.2	4.3	0.7	5.4	ns
		V _{CC} = 4.5 V to 5.5 V	0.5	1.8	3.3	0.5	4.2	ns
C _{PD}	power dissipation capacitance	per gate; $V_I = GND$ to V_{CC} [3]	-	14	-	-	-	pF

[1] Typical values are measured at nominal V_{CC} and at T_{amb} = 25 °C.

 t_{pd} is the same as t_{PLH} and t_{PHL} . C_{PD} is used to determine the dynamic power dissipation (P_D in μ W). $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o)$ where:

f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

 V_{CC} = supply voltage in V;

N = number of inputs switching; $\sum (C_L \times V_{CC}^2 \times f_0)$ = sum of outputs.

Dual 2-input NAND gate

11.1. Waveforms and test circuit

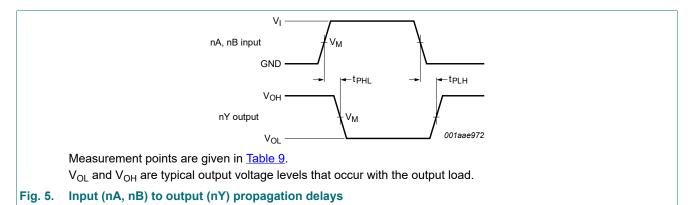
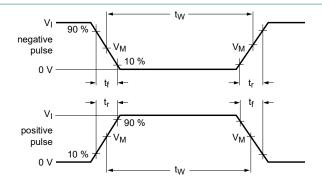
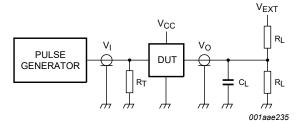


Table 9. Measurement points

Supply voltage	Input	Output
V _{CC}	V _M	V _M
1.65 V to 1.95 V	0.5V _{CC}	0.5V _{CC}
2.3 V to 2.7 V	0.5V _{CC}	0.5V _{CC}
2.7 V	1.5 V	1.5 V
3.0 V to 3.6 V	1.5 V	1.5 V
4.5 V to 5.5 V	0.5V _{CC}	0.5V _{CC}

Dual 2-input NAND gate





Test data is given in <u>Table 10</u>.

Definitions for test circuit:

R_L = Load resistance;

C_L = Load capacitance including jig and probe capacitance;

 R_{T} = Termination resistance should be equal to output impedance Z_{o} of the pulse generator;

V_{EXT} = Test voltage for switching times

Fig. 6. Test circuit for measuring switching times

Table 10. Test data

Supply voltage	Input		Load		V _{EXT}
V _{CC}	V _I	t _r , t _f	CL	R _L	t _{PLH} , t _{PHL}
1.65 V to 1.95 V	V _{CC}	≤ 2.0 ns	30 pF	1 kΩ	open
2.3 V to 2.7 V	V _{CC}	≤ 2.0 ns	30 pF	500 Ω	open
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open
4.5 V to 5.5 V	V _{CC}	≤ 2.5 ns	50 pF	500 Ω	open

12. Package outline

TSSOP8: plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm SOT505-2

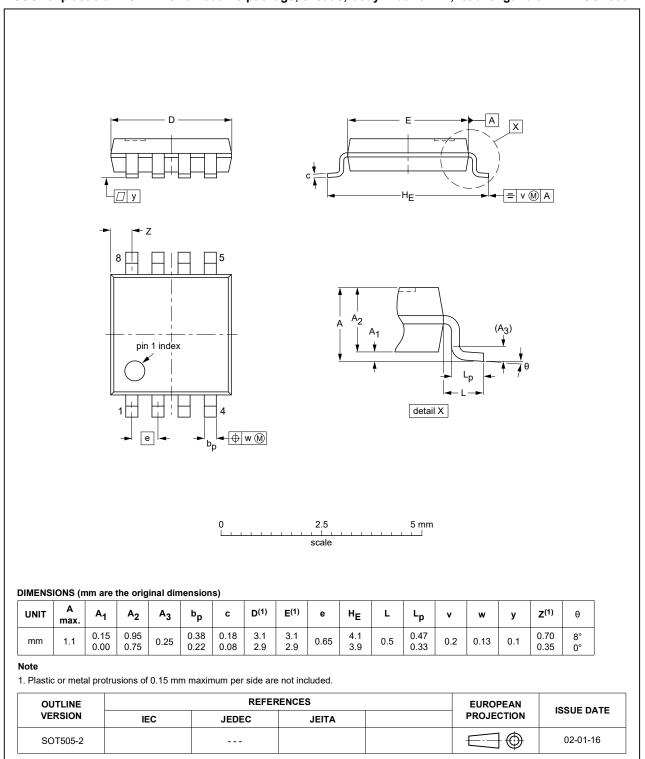


Fig. 7. Package outline SOT505-2 (TSSOP8)

Dual 2-input NAND gate

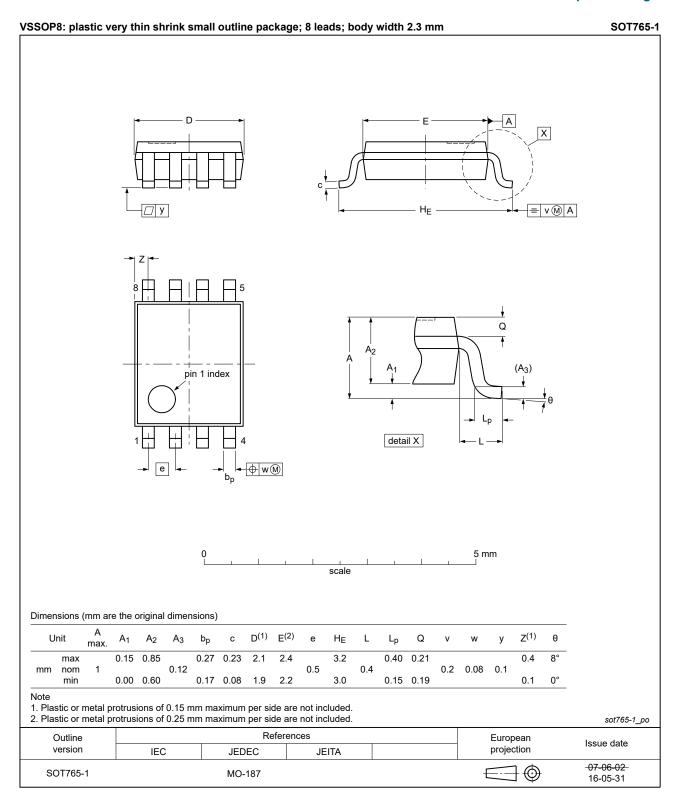


Fig. 8. Package outline SOT765-1 (VSSOP8)

Product data sheet

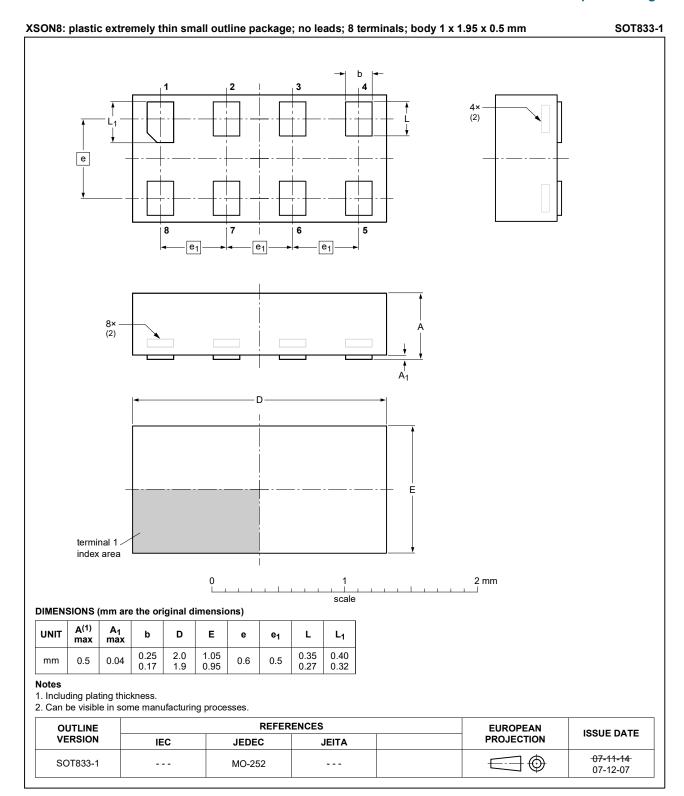


Fig. 9. Package outline SOT833-1 (XSON8)

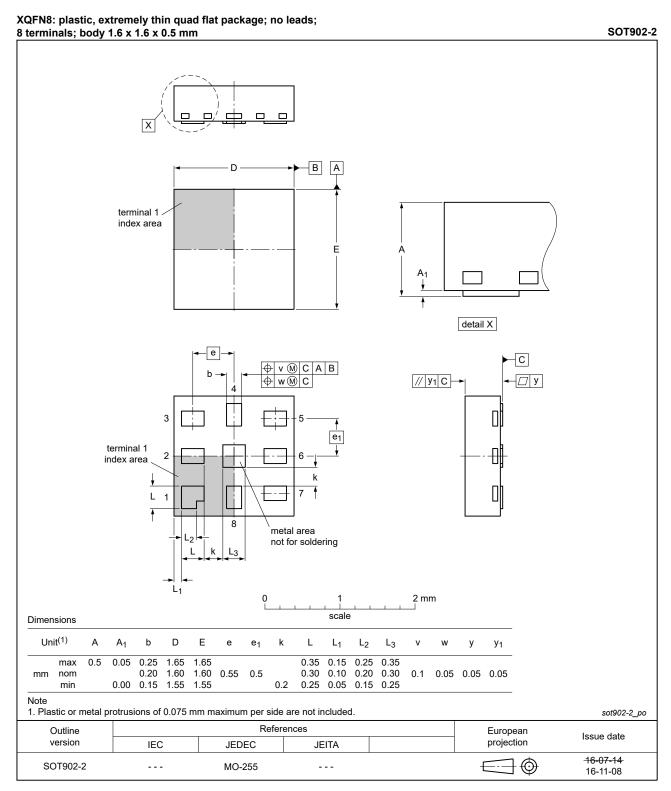


Fig. 10. Package outline SOT902-2 (XQFN8)

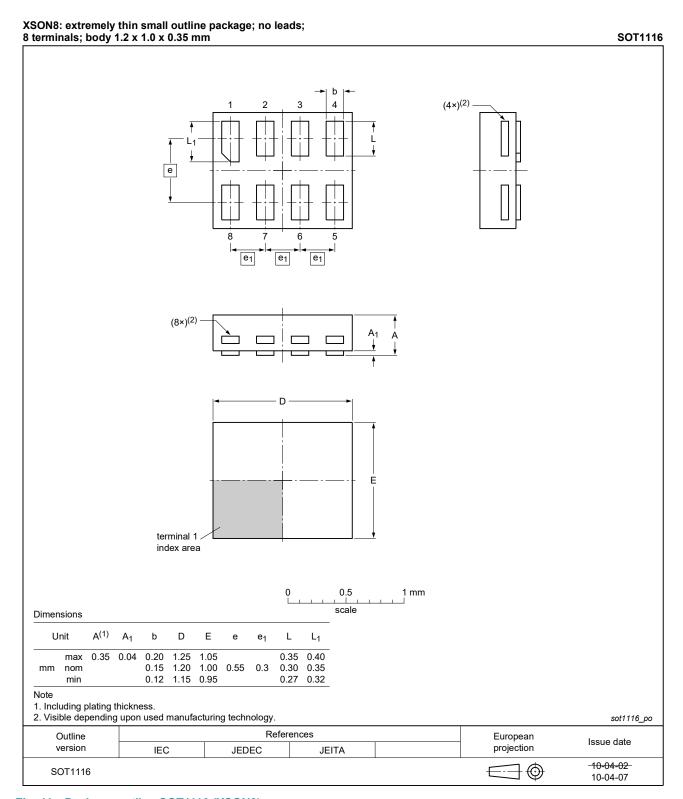


Fig. 11. Package outline SOT1116 (XSON8)

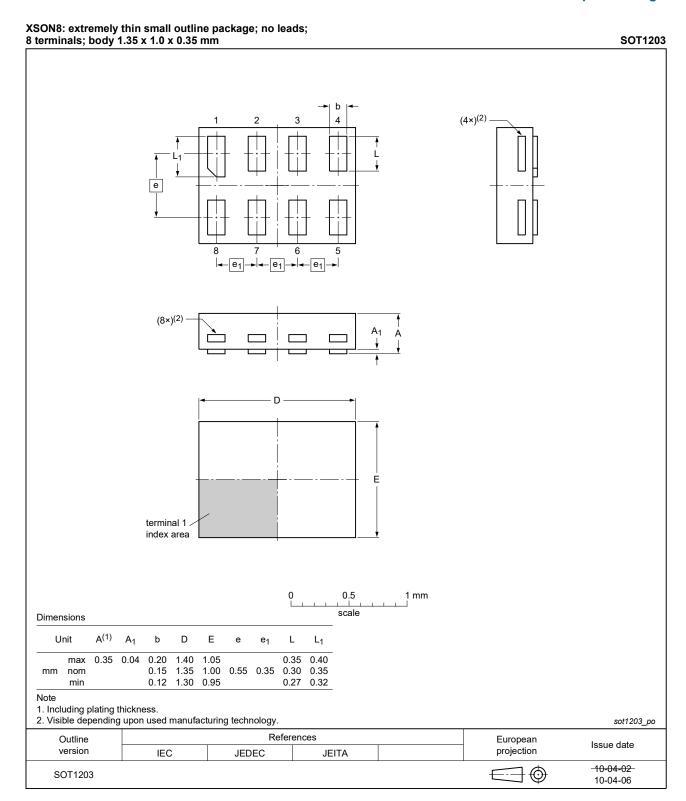


Fig. 12. Package outline SOT1203 (XSON8)

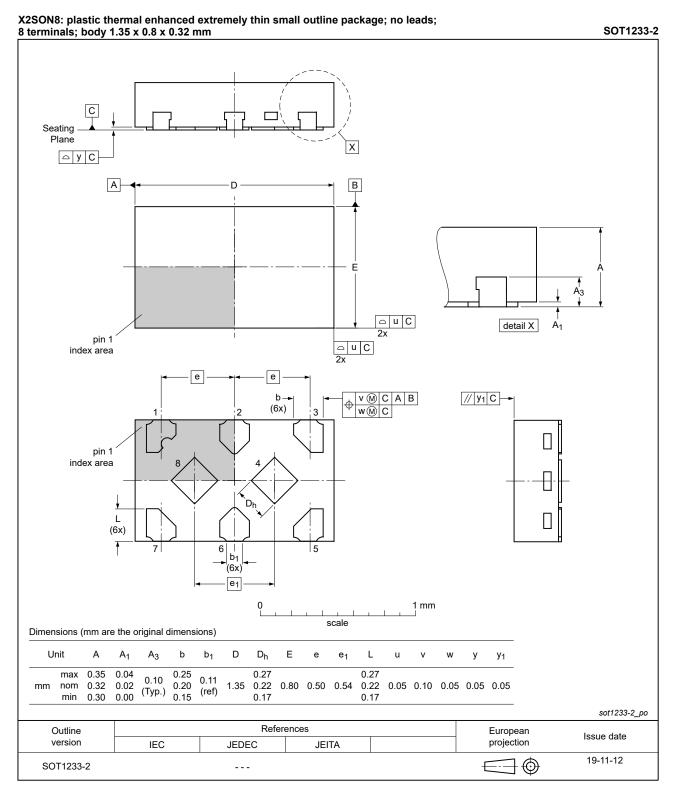


Fig. 13. Package outline SOT1233-2 (X2SON8)

Dual 2-input NAND gate

13. Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charged Device Model
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
НВМ	Human Body Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes	
74LVC2G00 v.18	20240508	Product data sheet	-	74LVC2G00 v.17	
Modifications:	Type number 74LVC2G00GF (SOT1089/XSON8) removed.				
74LVC2G00 v.17	20230814	Product data sheet	-	74LVC2G00 v.16	
Modifications:	<u>Section 2</u> : ESD specification updated according to the latest JEDEC standard.				
74LVC2G00 v.16	20220620	Product data sheet	-	74LVC2G00 v.15	
Modifications:	 SOT1233 (X2SON8) package changed to SOT1233-2 (X2SON8) package. <u>Table 5</u>: P_{tot} total power dissipation and derating values have been updated. <u>Section 1</u> and <u>Section 2</u> updated. 				
74LVC2G00 v.15	20170703	Product data sheet	-	74LVC2G00 v.14	
Modifications:	 The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia. Legal texts have been adapted to the new company name where appropriate. Fig. 13: Package outline drawing for SOT1233 has changed. Type number 74LVC2G00GD removed. 				
74LVC2G00 v.14	20161212	Product data sheet	-	74LVC2G00 v.13	
Modifications:	<u>Table 7</u> : The maximum limits for leakage current and supply current have changed.				
74LVC2G00 v.13	20161028	Product data sheet	-	74LVC2G00 v.12	
Modifications:	Added type number 74LVC2G00GX (SOT1233/X2SON8)				
74LVC2G00 v.12	20130408	Product data sheet	-	74LVC2G00 v.11	
Modifications:	For type number 74LVC2G00GD XSON8U has changed to XSON8.				
74LVC2G00 v.11	20120622	Product data sheet	-	74LVC2G00 v.10	
Modifications:	For type number 74LVC2G00GM the SOT code has changed to SOT902-2.				
74LVC2G00 v.10	20111130	Product data sheet	-	74LVC2G00 v.9	
Modifications:	Legal pages updated.				
74LVC2G00 v.9	20100608	Product data sheet	-	74LVC2G00 v.8	
74LVC2G00 v.8	20091026	Product data sheet	-	74LVC2G00 v.7	
74LVC2G00 v.7	20080610	Product data sheet		74LVC2G00 v.6	
74LVC2G00 v.6	20080220	Product data sheet	-	74LVC2G00 v.5	
74LVC2G00 v.5	20070904	Product data sheet	-	74LVC2G00 v.4	

Dual 2-input NAND gate

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at https://www.nexperia.com.

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Dual 2-input NAND gate

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